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Dr Paul Evans

University of Nottingham

**Overview of Centre for Power Electronics:  
Tranche 2 Topics**

# The Research Projects

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Switch Optimisation

Converter Architectures

Heterogeneous Integration

Reliability and Health  
Management

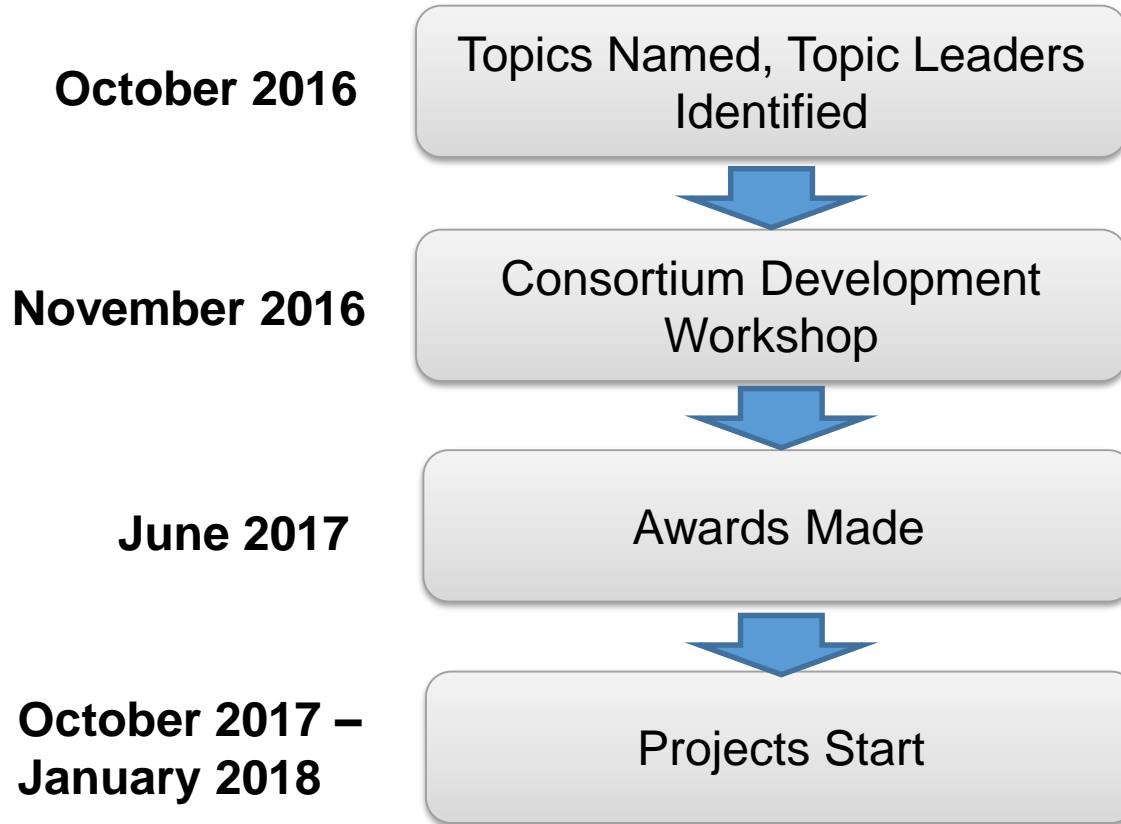
Virtual Prototyping

**Supporting development and  
application of wide band-gap  
semiconductors**

£6M total funding over 3 years.

# Background to Research Proposals

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# Switch Optimisation (SO)

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**Dr. Peter M. Gammon**



**SiC IGBT design (5-15kV), processing techniques, testing and benchmarking**



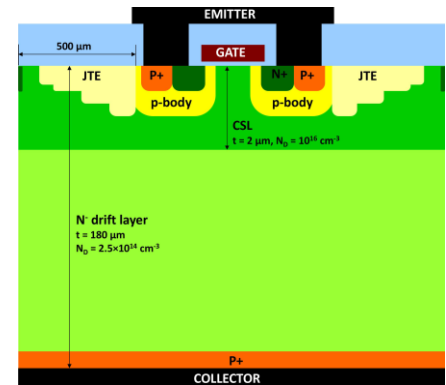
# Overview and Motivation (SO)

## Opportunity to innovate in field

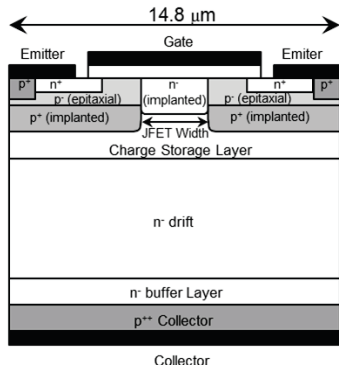
- Only 4 groups internationally have developed SiC IGBTs
- Potential to develop early IP

## Opportunities for 11kV grid applications & transport

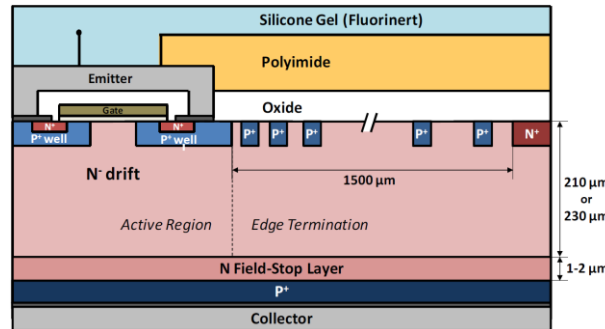
## Builds on SiC MOSFET, and Si Trench IGBT work in Tranche 1 project



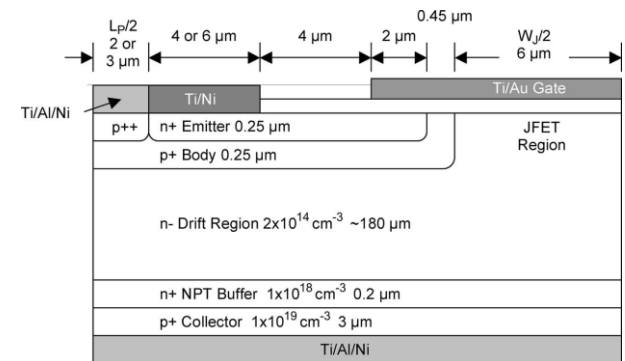
2016: Chowdhury/Chow, RPI, USA (20kV)



2013: Yonezawa, NAIST, Japan (16kV)



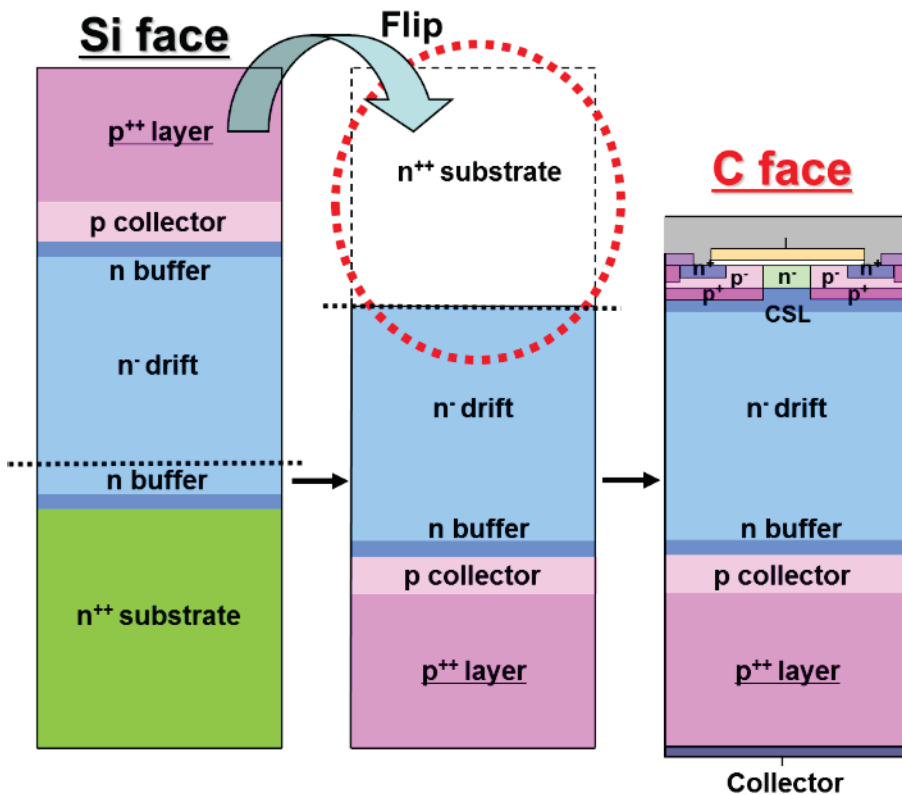
2014: Van Brunt, Cree, USA (27kV)



2010: Wang/Cooper, Purdue – the first n-IGBT (20kV)

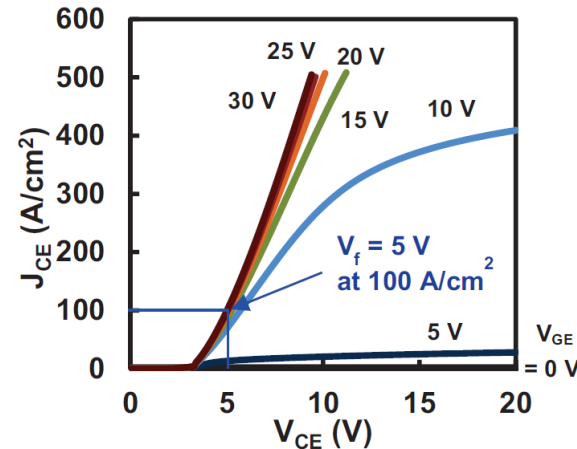
# Research Content (SO)

## N-channel SiC IGBT Development



Our own SiC IGBTs will include:

- **15 kV demonstrators**, comparable to SOA.
- **5-10kV designs**, lower than current SOA, benchmarking to SiC MOSFETs
- **Experimental designs:** Trench gates, field stop regions, integrated MOSFET.



# Switch Optimisation Theme Workshop

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## SiC power semiconductor devices:

*The current landscape and the challenges of scaling to 10 kV+*

- **Are SiC devices realising their promise?** What are the applications in which market penetration is occurring?
- **What weaknesses are holding back current devices?** Reliability, cost, proven legacy, voltage range?
- **What does the future hold?** Reliability, scaling processes, scaling up voltages.

Discussion of the above with panel made up from industry and academia: Dr Hamada, **Toyota**; Dr Sharma, **Dynex Semiconductor**; Dr Trajkovic, **Cambridge Microelectronics**; and Prof Richard McMahon, **University of Warwick**.

Details of the **CPE SO THEME**: developing 10kV+ SiC IGBTs.

# Converter Architectures (CA)

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**Professor Xibo Yuan**

**Imperial College  
London**



**Enabling technologies for higher voltage, higher power and high frequency WBG power conversion**



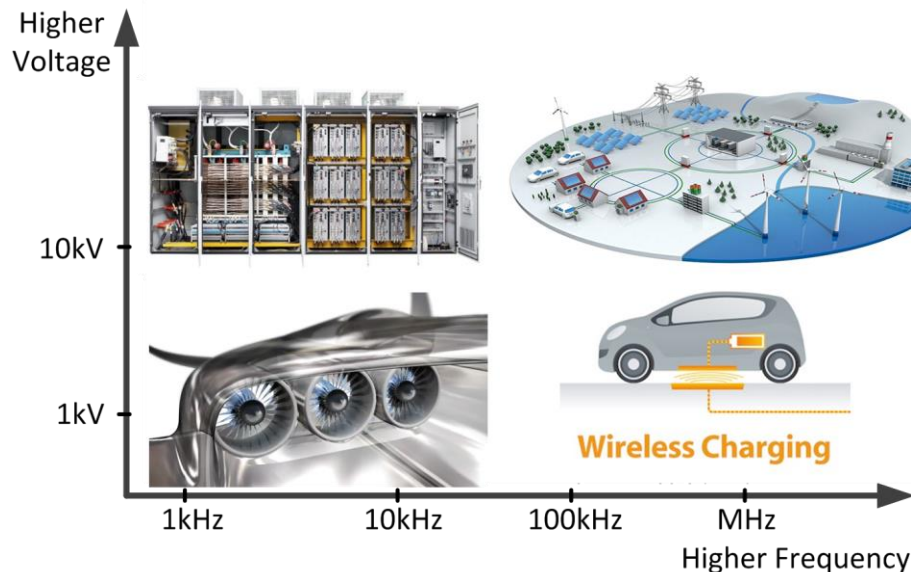


# Overview and Motivation (CA)

- Higher voltage devices switching faster
  - Topologies to mitigate  $dv/dt$  effects
  - Topologies for medium voltage power conversion
  - Topologies for MHz power conversion
- Passive components at HF, high power density
- High bandwidth digital control
- Deliver high profile demonstrator platform



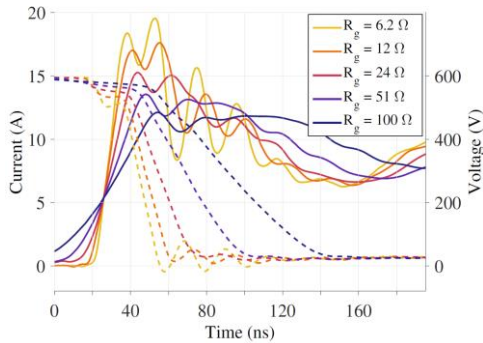
13MHz, 500W  
wireless power converter



# Research Content (CA)

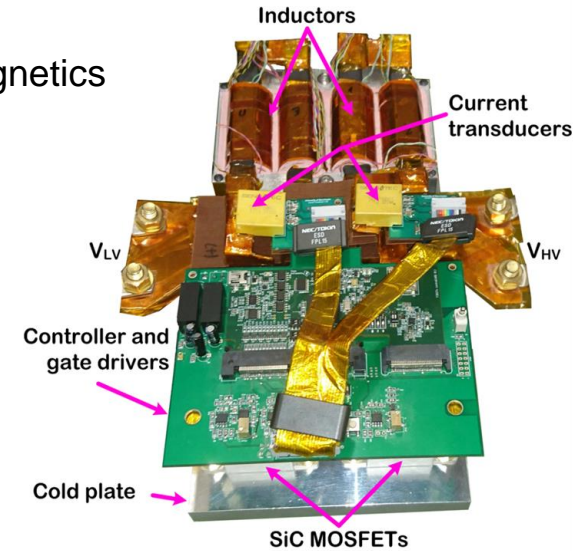
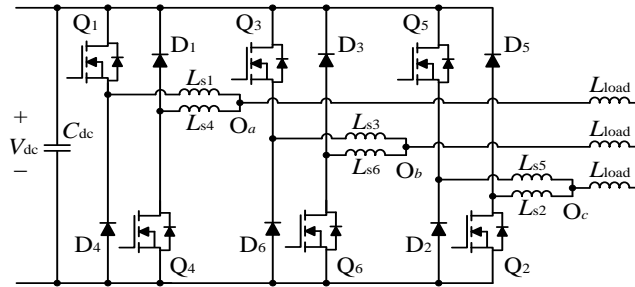
## WP1: Converter Topologies

- Topology modification for HF
- New HF topology development
- Parasitic optimization
- Multilevel topologies



## WP2: Passive Components

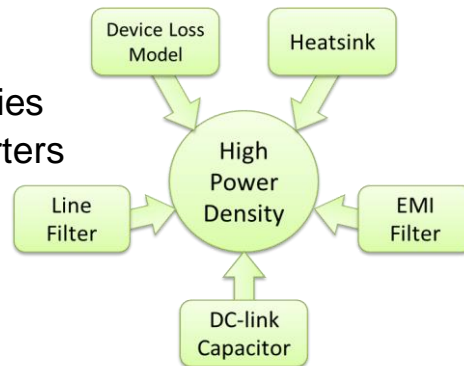
- Topology specific conventional magnetics
- Air cored magnetics



80kW DC/DC converter

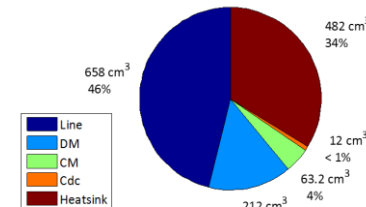
## WP3: Advanced Control

- Digital control at high frequencies
- Strategies for multilevel converters



## WP4: Holistic Design Optimization

- Identify design tradeoffs
- Produce optimal design guidelines: efficiency, power density



## WP5: Demonstrator

# Workshop

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- Hear about capabilities of state-of-the-art WBG converters and recent achievements of the Centre's converters theme.
- Find out how we push the frequency/voltage/power boundaries.
- Discuss emerging applications for WBG converters.
- Participate and define the WBG converter demonstrator of the Converter Architecture project.

# Heterogeneous Integration (HI)

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University of  
Nottingham  
UK | CHINA | MALAYSIA

**Prof. Lee Empringham**



Loughborough  
University

## **Developing Integrated Commutation Cell Modules**

Highly optimised power conversion building blocks that underpin system level application of WBG devices: better performance, lower cost, improved reliability.

# Overview and Motivation (HI)

## Immediate environment around semiconductors is key:

- Electromagnetic design
- Thermal management
- Mechanical design and assembly

## Develop Integrated Modules

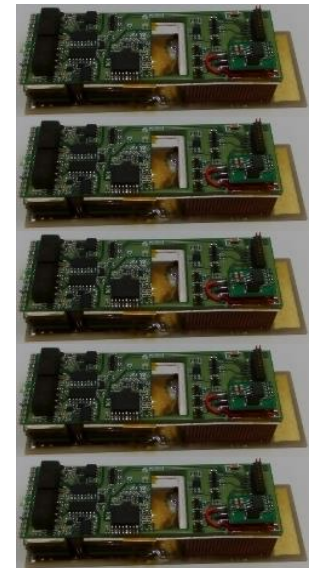
- Power Devices
- Filtering and Shielding
- Thermal management
- Gate-driving & control.

## A modular approach for end users

- Converter in package

## Manufacturing and Assembly

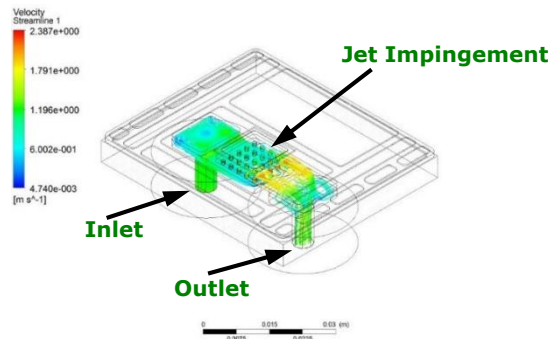
- Design for manufacture, cost



# Research Content (HI)

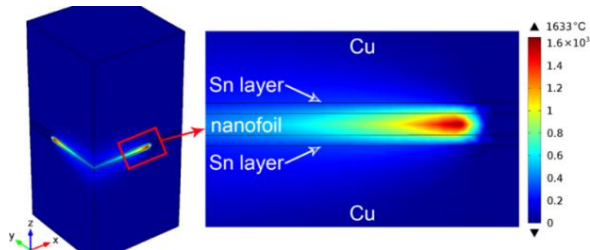
## WP1: Design and Modelling

- Concurrent Electromagnetic, Thermal, Mechanical
- EMI, stress optimization



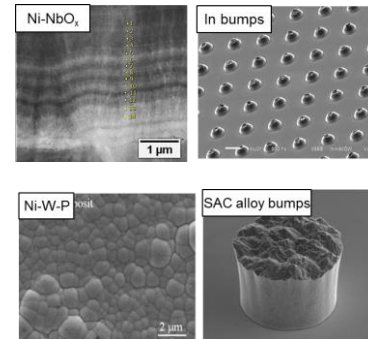
## WP3: Structural Embedding Process

- 3D layered/ laminated structures
- Embedded actives, passives
- Manufacturing process development



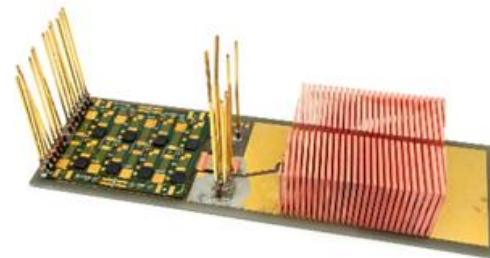
## WP2: Materials and Interconnection

- Interconnect techniques
- Additive/subtractive manufacturing processes
- Material interactions



## WP4: Demonstrator

- Demonstrator modules
- Showcase developments in WP1-WP3



# Workshop

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## **Presentation**

- Outline the need for higher levels of integration in order to fully utilise WBG semiconductors
- Hear about the aims, present and future work of the HI theme.

## **Group Discussion**

- Discuss the different levels of integration and their implications
  - How much integration is appropriate for different industries / applications.
- Discuss the key issues and technological barriers to be faced
  - How important are the issues
  - Discuss and identify Industry derived requirements

## **Engage**

- Build links with researchers working on the project and discover ways to get involved.

# Reliability and Health Management (RHM)

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**Dr. Layi Alatise**



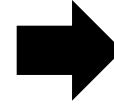
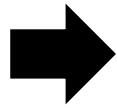
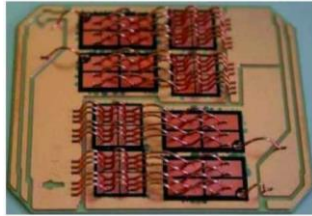
**Enhancing reliability in high power density WBG converters using on-line condition monitoring and health management**



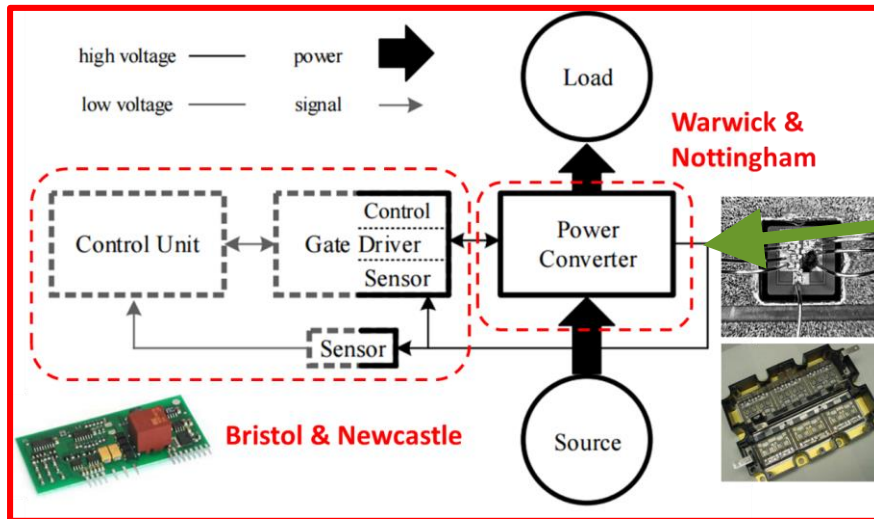


# Overview and Motivation (RHM)

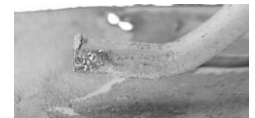
System Wide, Multi-Level Challenge



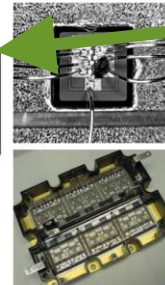
Enable power converters with in-built technologies for lifetime estimation and failure prediction



Solder Cracks

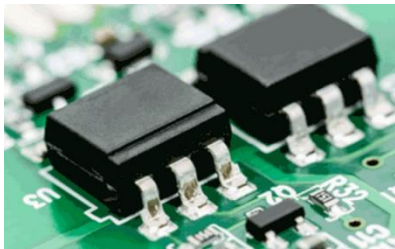
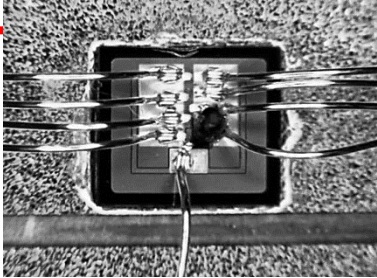


Wirebond Lift-off

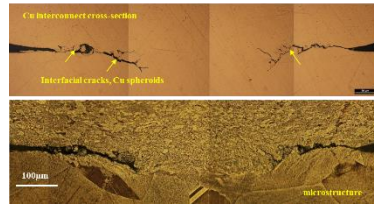
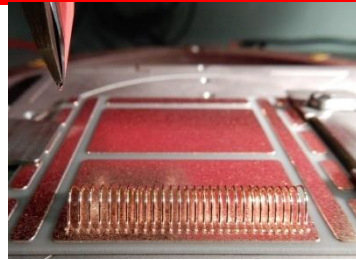


Electrothermal Failure

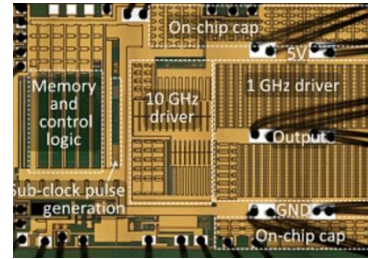
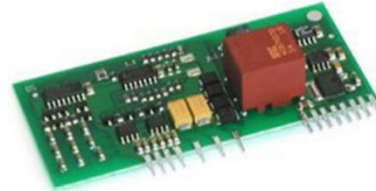
# Research Content (RHM)



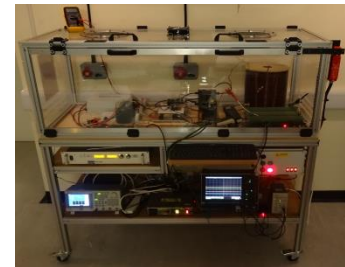
Discrete Device  
WP1



Module level  
WP2



Gate Driving  
WP3



Converter application  
demonstrator WP4

- Identify and characterise degradation indicators in GaN and SiC devices
- Package level reliability assessment
- Gate-drive integrated condition monitoring and health management
- System level demonstrator

# RHM Workshop

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- Industrial speakers from Grid and Automotive industries
- ***Prospects for Condition Monitoring in Automotive Traction Applications*** by Dr George Petkos, AVL Powertrains UK Ltd
- ***Prospects for Condition Monitoring for Grid Connected Converters*** by Dr Saeed Jahdi, GE Grid Solutions UK Ltd
- Discussion and panel debate on the possibilities and prospects for condition monitoring

# Virtual Prototyping (VP)



University of  
Nottingham  
UK | CHINA | MALAYSIA

Dr. Paul Evans



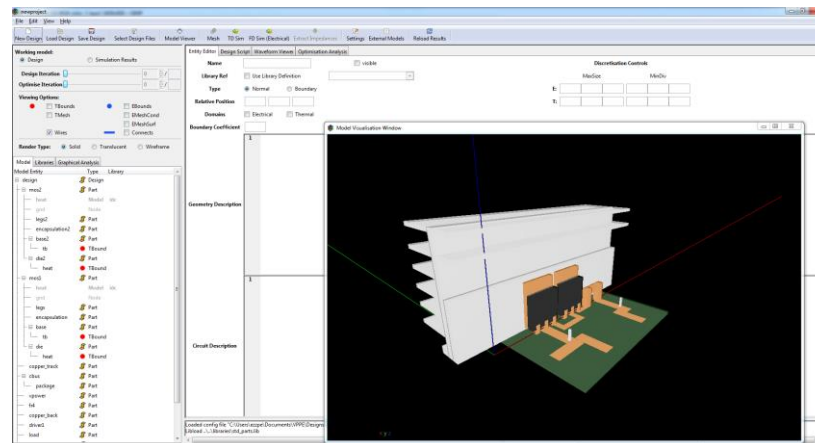
University of  
BRISTOL



UNIVERSITY of  
GREENWICH

Develop design methods for fast multi-domain simulation and optimisation of power electronic systems

Demonstrator in form of software application



# Overview and Motivation (VP)

High frequency, high power density designs sensitive to physical design

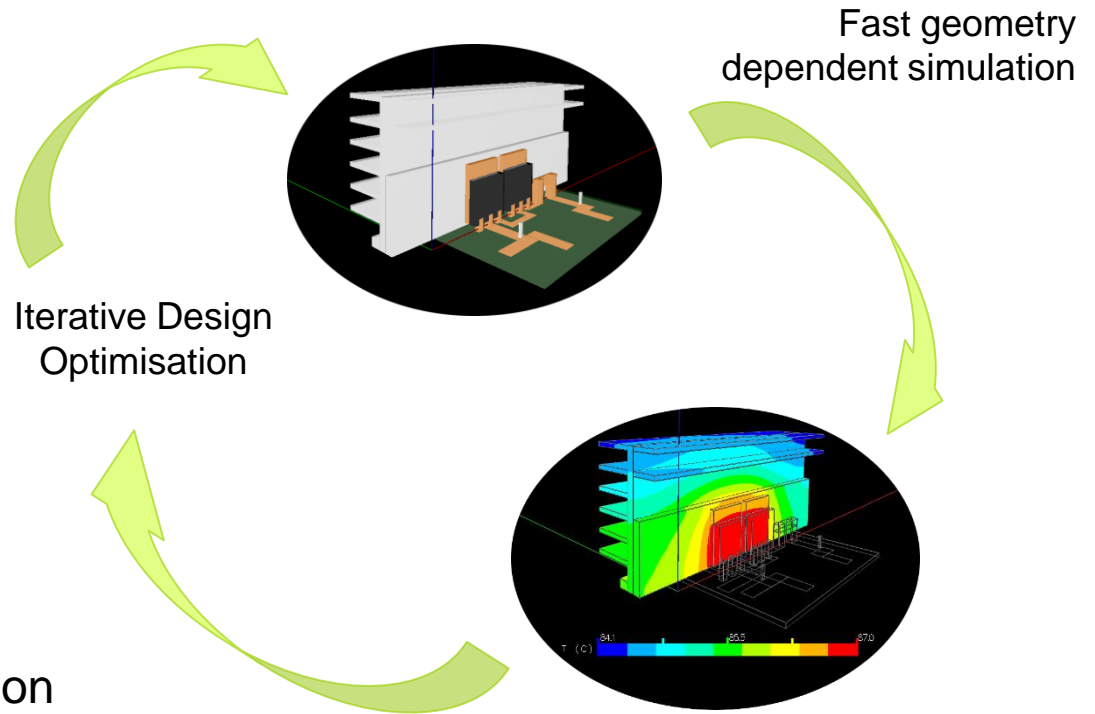
Coupled, Multi-Domain Effects

- Semiconductor
- Electrical/Electromagnetic
- Thermal
- Mechanical/Reliability

Need design tools that can predict these effects

Accelerated time-domain simulation

Fast design tools for non-specialist

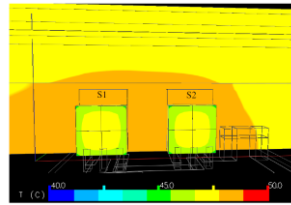
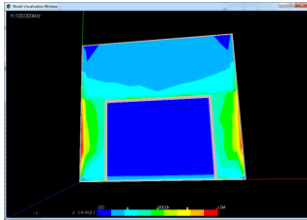


Coupled analysis in  
Electrical,  
Electromagnetic, Thermal  
and Mechanical Domains

# Research Content (VP)

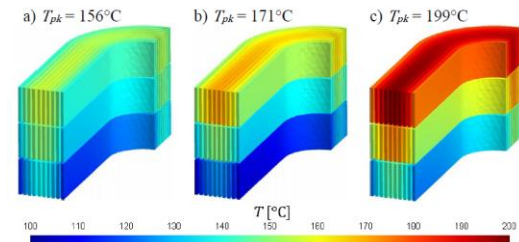
## WP1: Fast Electro-Thermal Modelling

- 3D-physical electromagnetic-thermal system models using MOR techniques.
- Embedding non-linear passive component models.



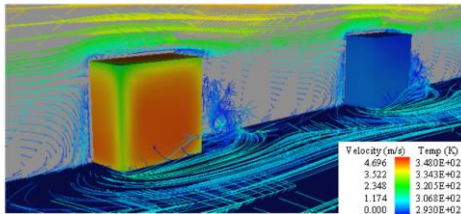
## WP2: Magnetic Component Loss Models

- Estimate losses in magnetic materials/components using lumped parameter methods.



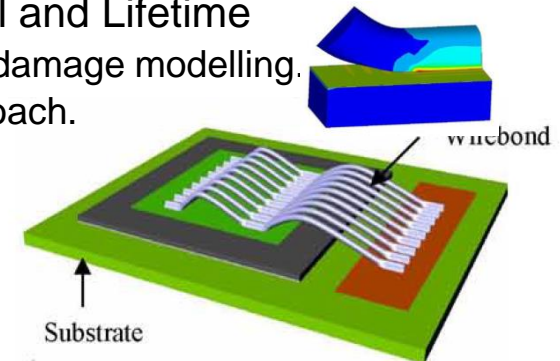
## WP3: Convective Heat Transfer

- Flow networks.
- Localised, "Ultra-Fast" CFD.

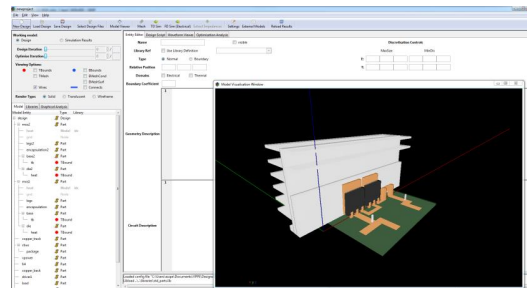


## WP4: Mechanical and Lifetime

- Stress-strain & damage modelling.
- Multiscale approach.



## WP5: Demonstrator



# VP Workshop

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**Virtual Prototyping:** Developing design and simulation tools for future power electronic systems

## Presentation

- Hear about the VP project in more detail.

## Discussion

- How are design tools currently used, what limitations are present in current commercial offerings?
- What does the ideal power electronic design/simulation tool look like? Help guide the project.

## Future Engagement

- Build links with researchers working on the project and register to gain access to project outputs.

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Five coupled projects with  
common goal

One workshop per project  
after break

Choose one to attend

Switch Optimisation

Converter Architectures

Heterogeneous Integration

Reliability and Health  
Management

Virtual Prototyping